



## Material Content Data Sheet



<b>Sales Product Name</b>		BSZ300N15NS5		<b>Issued</b>		4. July 2019		
<b>MA#</b>		MA001327834						
<b>Package</b>		PG-TSDSON-8-26		<b>Weight*</b>		36.76 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.629	1.71	1.71	17112	17112
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		67	
	non noble metal	zinc	7440-66-6	0.010	0.03		268	
	non noble metal	iron	7439-89-6	0.197	0.54		5352	
wire	non noble metal	copper	7440-50-8	7.988	21.73	22.31	217295	222982
	noble metal	gold	7440-57-5	0.028	0.08	0.08	750	750
encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1002	
	plastics	epoxy resin	-	1.897	5.16		51610	
	inorganic material	silicondioxide	60676-86-0	16.486	44.83	50.09	448452	501064
leadfinish	non noble metal	tin	7440-31-5	0.395	1.08	1.08	10752	10752
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	553	553
solder	non noble metal	tin	7440-31-5	0.019	0.05		510	
	noble metal	silver	7440-22-4	0.023	0.06		637	
	non noble metal	lead	7439-92-1	0.895	2.43	2.54	24334	25481
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001	0.00		34	
	non noble metal	zinc	7440-66-6	0.005	0.01		138	
	non noble metal	iron	7439-89-6	0.101	0.28		2755	
	non noble metal	copper	7440-50-8	4.112	11.19	11.48	111864	114791
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32	
	non noble metal	zinc	7440-66-6	0.005	0.01		128	
	non noble metal	iron	7439-89-6	0.094	0.26		2556	
	non noble metal	copper	7440-50-8	3.816	10.38	10.65	103799	106515
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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